

Compact
Model

3DAOI

AUTOMATED OPTICAL INSPECTION

TR7700QC SII SERIES



High-Performance 3D Inspection
of Components and Solder Joints



Industry-leading Inspection Speed
up to 57 cm²/sec



User-Friendly Programming
and Flexible Algorithms



Smart Factory
Ready



40
mm
3D Height Range
up to 40 mm



Real Time SPC
Trends



TRI
innovation

*Optional feature.

TR7700QC SII S



Core Features 3D AOI Solution

The TR7700QC SII 3D AOI is equipped with essential inspection functionalities for multiple electronics manufacturing industry applications. The Smart 3D AOI features user-friendly programming for easy setup, flexible inspection algorithms, and compliance with the latest Smart Factory standards.



High Speed
up to 57 cm²/s



Tall Component
Inspection



AI-powered
Inspection



Flexible
Algorithms



Foreign Material
Detection



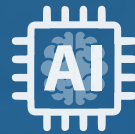
Board Warpage
Control

Smart Programming

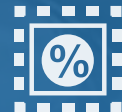
Realize seamless programming, improve your production efficiency and quickly setup your production line Inspection with TRI's Smart Programming. The user-friendly programming promotes ease of use and maintenance to achieve precise and accurate inspection results.



Scan
Board



Setup
Inspection



Inspect
Board

Full Coverage Defect Detection

The 3D AOI system is powered by IPC-610-compliant algorithms that inspect the most intricate solder joint defects, including THT components. Interactive 3D models help operators quickly review found defects, such as lifted BGA components, IC leads, connectors, switches, and other mounted devices.



SOT Inspection



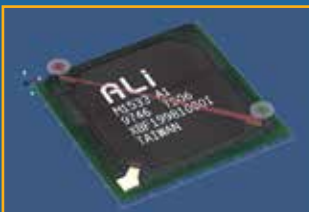
ECU Connector



True 3D Inspection



Character Recognition



IC Inspection



Lead Inspection



Solder Joint Inspection



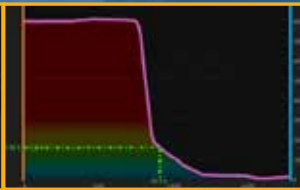
Chip Shift

Accurate Height Measurements

The TR7700QC SII can accurately measure the solder and component height. The 3D AOI also features the Multi-Step Function, which enables efficient inspection of components with different heights, up to 40 mm.



3D Height Profile



Tall Component Inspection

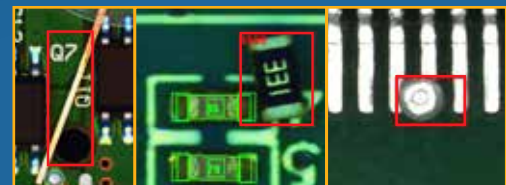
AI-Powered Inspection

Boost your production's intelligence with TRI's AI-powered Inspection solutions. TRI offers an array of specialized defect detection AI algorithms, AI Training Tools, AI Servers, and a Smart Repair Station.



Foreign Material Detection

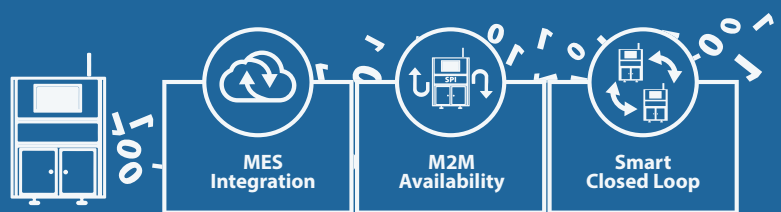
Minimize false calls and perform no escape inspections with TRI's Foreign Material Detection feature. TRI's Optical Inspection solutions utilize auto-learning of PCB designs to detect and identify additional components, solder balls, fibers, and other foreign objects, effectively eliminating these defects.



Foreign Object Detection

Smart Factory Ready

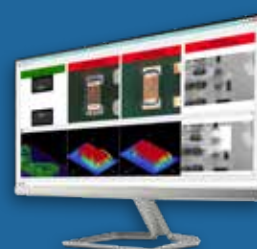
TRI's Inspection Solutions promote full traceability and data exchange by generating Big Data for your MES Applications, which is essential for optimizing your production's yield rate, enabling the Connected Factory. TRI's solutions comply with Industry 4.0 standards like the IPC-Hermes-9852, the IPC-DPMX, and the Connected Factory Exchange (IPC-CFX).



Yield Management System 4.0



Yield Management System 4.0 (YMS 4.0) by TRI is a centralized monitoring software that improves production line yield rates. It provides real-time visibility, remote control, and alarms of the inspection machines in the production line.

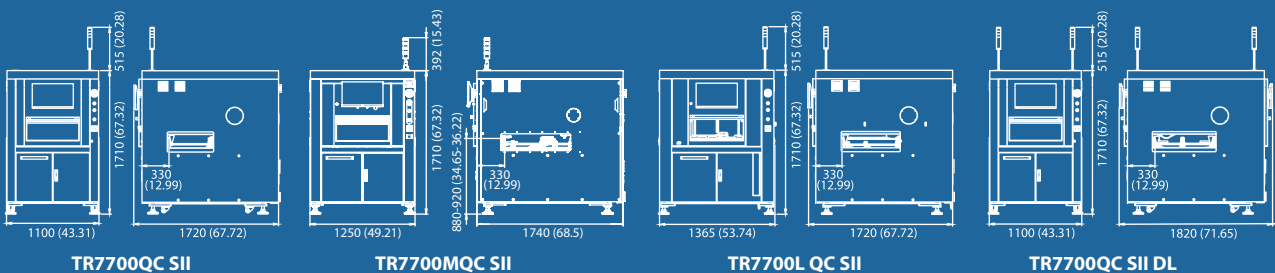


Defect Image Analyzer

Model	TR7700QC SII	TR7700MQC SII	TR7700L QC SII	TR7700QC SII DL
Imaging System	High Speed Camera Optical Resolution 12 MP Inspection Speed 10 µm / 12 µm / 15 µm Max. 3D Height Range 10 µm: 25 cm ² /sec, 12 µm: 37 cm ² /sec, 15 µm: 57 cm ² /sec 3D Technology 40 mm (1.57 in.) Lighting Quad Digital Fringe Projectors Multi-phase True Color LED			
Pre-/Post-Reflow Inspection Functions	Component Defects Missing, Tombstoning, Billboarding, Polarity, Rotation, Shift, Wrong Marking (OCV), Defective, Upside Down, Extra Component, Foreign Material, Lifted Component Solder Joint Defects Solder Fillet Height, Solder Volume %, Excess Solder, Insufficient Solder, Bridging, Through-hole Pins, Lifted Lead, Golden Finger Scratch/ Contamination			
X-Y-Z Axis Control	Ballscrew + AC Servo with Motion Controller			
X-Y-Z Axis Resolution	1 µm			
Inspect Performance (on Calibration Target)	Height Repeatability 3σ < 1 µm Height Accuracy +/- 2 µm			
Min PCB Size	50 x 50 mm (1.97 x 1.97 in.)			
Max PCB Size	510 x 460 mm (20.08 x 18.11 in.)	660 x 690 mm (25.98 x 27.17 in.)	765 x 610 mm (30.12 x 24.02 in.)	510 x 310 mm x 2 lanes (20.08 x 12.20 in.) 510 x 590 mm x 1 lane (20.08 x 23.23 in.)
PCB Thickness	0.6 - 5 mm (0.02 - 0.20 in.)			
PCB Transport Height ⁽¹⁾	880 - 920 mm (34.65 - 36.22 in.)			
Max PCB Weight	3 kg (6.61 lb.) Optional: 5 kg (11.02 lb)		3 kg (6.61 lb.) Optional: 5 kg (11.02 lb) / 12 kg (26.46 lb)	3 kg (6.61 lb.) Optional: 5 kg (11.02 lb)
PCB Carrier / Fixing	Step Motor Driven			
Clearance	Top 50 mm (1.97 in.)			
	Bottom 40 mm (1.57 in.)			
	Edge 3 mm (0.12 in.) Optional: 4 mm (0.16 in.) / 5 mm (0.20 in.)			
Weight	910 kg (2,006.21 lb)	992 kg (2,186.99 lb)	1025 kg (2,259.74 lb)	960 kg (2,116.44 lb)
Power Requirement	200 - 240 VAC, single phase, 50 / 60 Hz, 3 kVA			
Communication Standard	SMEMA, SECS/GEM, IPC-CFX-2591, IPC-HERMES-9852			
Air Requirement	72 psi - 87 psi (5 - 6 bar)			
Optional	Barcode Scanner, Repair Station, Offline Editor, OCR, Yield Management System (YMS 4.0), Support Pin, AI Solutions (Requires GPU Upgrade)			

(1) Optional: 940-965 mm (SMEMA compatible)

Unit: mm (in.)



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